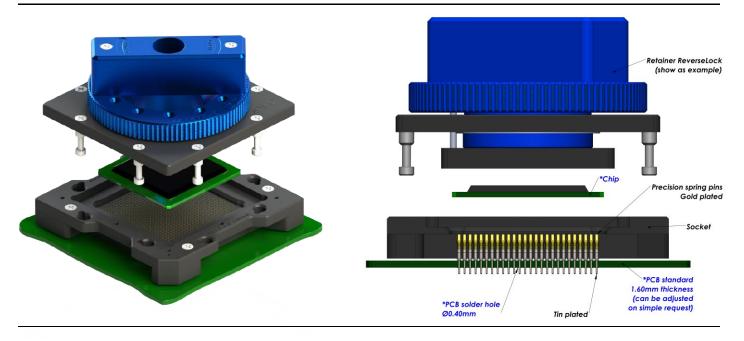
## **Through-hole (THT) soldering Test Socket**

For LGA / QFN / MLF / MLP / LCC Package **0.80 mm pitch** (from 0.80 mm up to 0.99 mm)





## E-tec Interconnect AG is the world leading Test socket manufacturer

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 0870			
Application	Through-hole technology	Force	30 gr
Mounting	THT	Current rating	1.8 A
Bandwidth (GHz@-1dB)	3.4 GHz	Capacitance pF	0.59 pF
Contact resistance	<100mOhm	Inductance nH	1.70 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	Through-hole	Mating cycles	100 K

## How to order

